



8.0A GLASS PASSIVATED SUPERFAST RECTIFIER

Features

- Fred Chip Planar Construction
- Superfast 28nS Recovery Time
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Soft Recovery Characteristics
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

Case: ITO-220A, Full Molded Plastic Terminals: Plated Leads Solderable per

MIL-STD-202, Method 208 Polarity: See Diagram

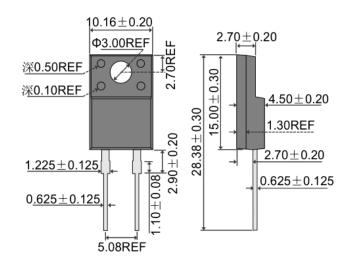
Weight: 1.9 grams (approx.)

Mounting Position: Any

Mounting Torque: 0.6 N.m Max.

Lead Free: For RoHS / Lead Free Version

ITO-220AC





Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

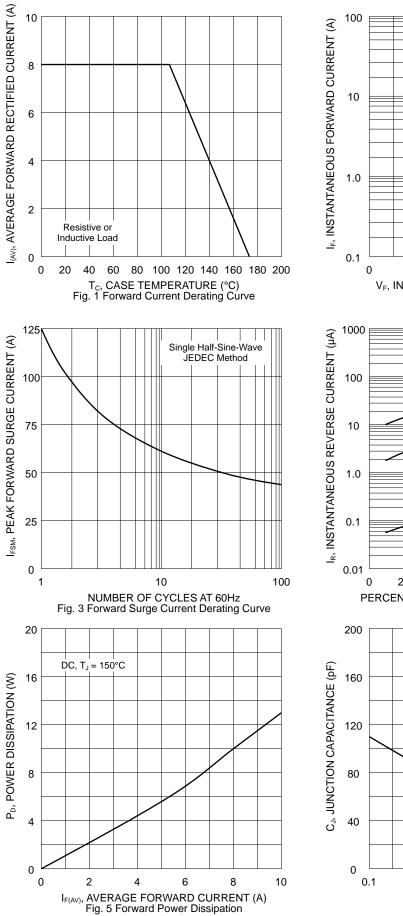
Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

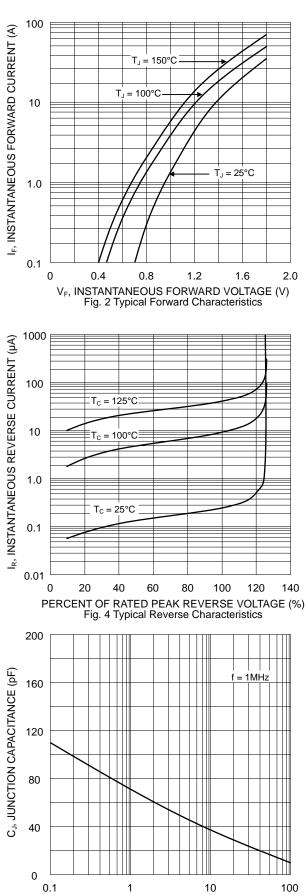
Characteristic	Symbol	MURF860	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		Vrrm Vrwm Vr	600	V
RMS Reverse Voltage		VR(RMS)	420	V
Average Rectified Output Current	$@T_C = 105^{\circ}C$	lo	8.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)		IFSM	125	А
Forward Voltage	$@I_F = 8.0A$	VFM	1.5	V
Peak Reverse Current At Rated DC Blocking Voltage	$@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	IRM	10 500	μΑ
Reverse Recovery Time (Note 1)		trr	28	nS
Typical Junction Capacitance (Note 2)		Cı	50	pF
Thermal Resistance Junction to Ambient Thermal Resistance Junction to Case		R JA R JC	73 3.0	°C/W
RMS Isolation Voltage, t = 1 min		Viso	1500	V
Operating and Storage Temperature Range		Тл, Тѕтс	-65 to +175	°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A. 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.





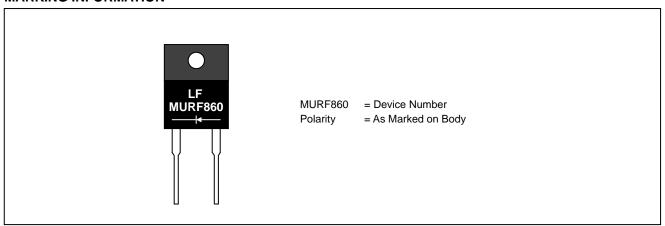




 $V_{\text{R}},$ DC REVERSE VOLTAGE (V) Fig. 6 Typical Junction Capacitance



MARKING INFORMATION



PACKAGING INFORMATION

BULK

Tube Size	Quantity	Inner Box Size	Quantity	Carton Size	Quantity	Approx. Gross Weight (KG)
L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

The full molded plastic package affords a major reduction of hardware as compared to a standard TO-220 package. However, precautions should be made in mounting procedure.

A conical washer should be used to apply proper force to the device. Screw should not be tightened with any type of air-forced torque or equipment that may cause crack on device package.

A layer of thermal grease or thermal pad in the interface will be considerably helpful for heat dissipation.

